

Introduction and Broader Impact

Microelectronics counterfeiting is:

- Estimated to cost the world semiconductor industry \$7.5 billion annually. [1]
- Considered to threaten the US military through infiltration into key electronics systems.
- Generally performed by sanding off the part numbers of old electronics components and/or resurfacing the parts prior to remarking with falsified information.

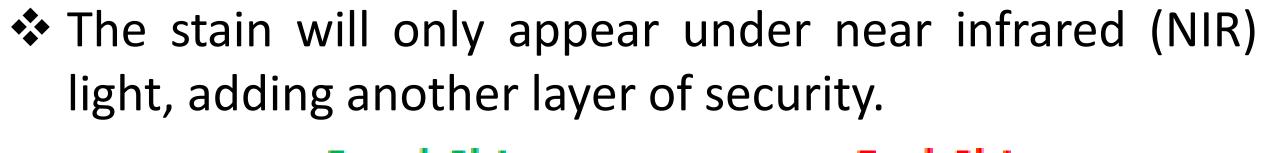
anti-counterfeiting development of improved The technology for microelectronics will:

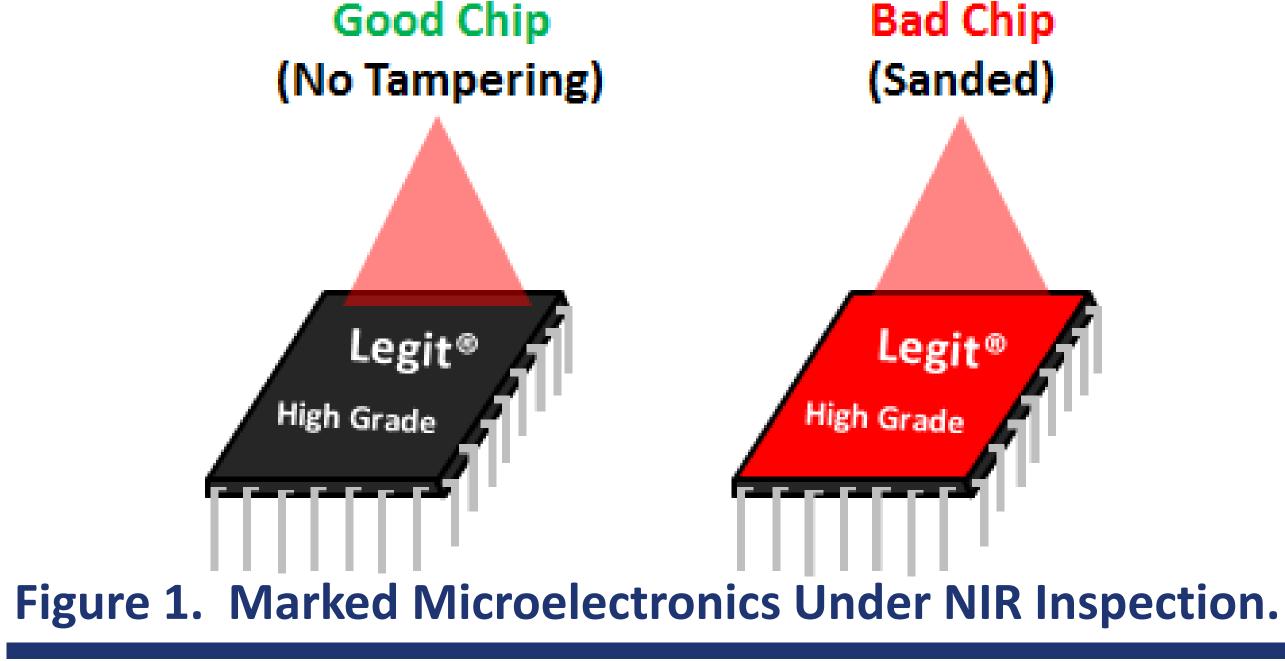
Result in more reliable consumer electronics.

Aid in national security.

Objective

Create a simple and effective means to mark authentic microelectronics with upconverting nanoparticle-loaded microcapsules which will break and stain the part upon sanding.





Counterfeit Prevention of Microelectronics through Covert Anti-Tamper Microcapsules

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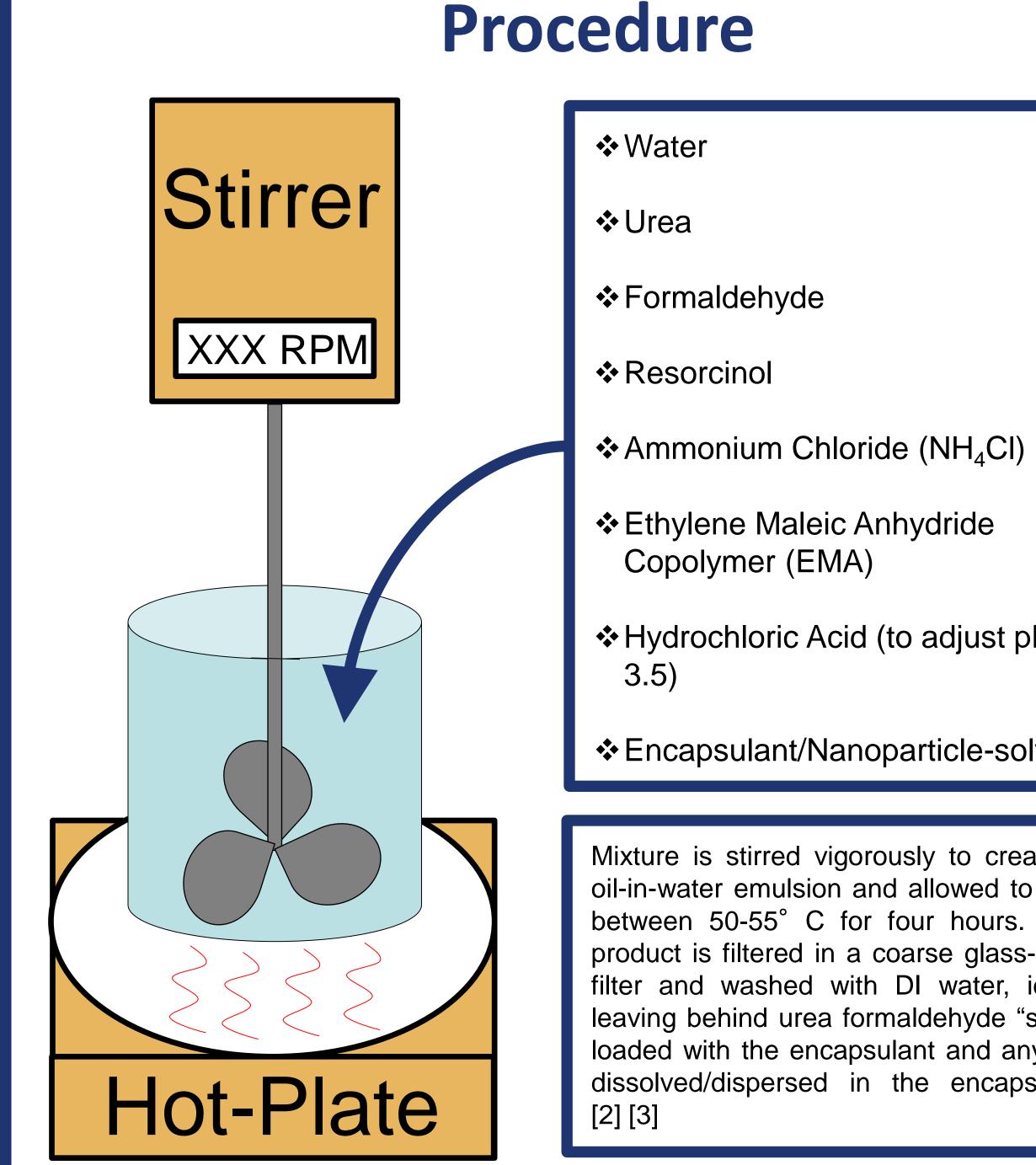


Figure 2. Schematic Procedure Representation. **Table I. Experimental Variables.**

Test Batch	Water (mL)	Urea (g)	Formal- dehyde (mL)	Resorc -inol (g)	NH ₄ CI (g)	EMA (g)	Encap- sulant (10mL)	RPM	Temp (°C)
1	41	1.16	2.0	0.083	0.083	0.83	Toluene	Stir Bar	N/A
2	41	1.16	2.0	0.083	0.083	0.83	Toluene	Stir Bar	50-55
3	41	1.16	2.0	0.083	0.083	0.83	Oleic Acid	Stir Bar	50-55
4	83+	1.16	2.0	0.083	0.083	0.41	Olive Oil	750	50-55
5	111	1.16	2.0	0.083	0.083	0.41	DCPD	500	50-55

Results and Conclusions

Test Batches 1-4 showed no evidence of microcapsule formation, but Test Batch 5 contained small numbers of broken microcapsules, suggesting dicylopentadiene (DCPD) as the only viable encapsulant tested.

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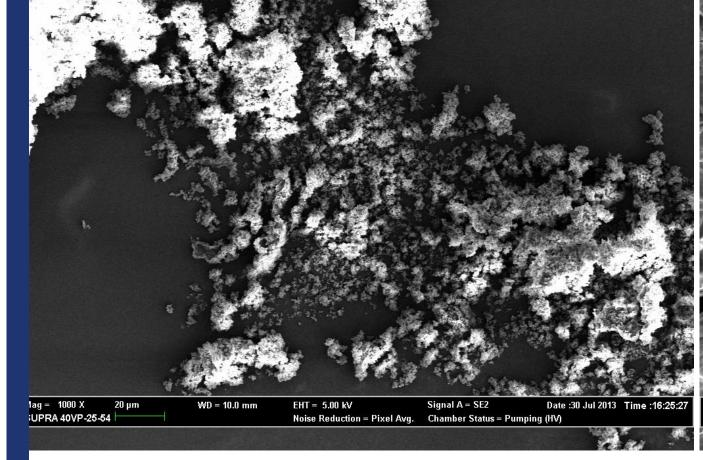


Figure 3. Test Batch 2 SEM Image.

Figure 4. Test Batch 4 SEM Image.

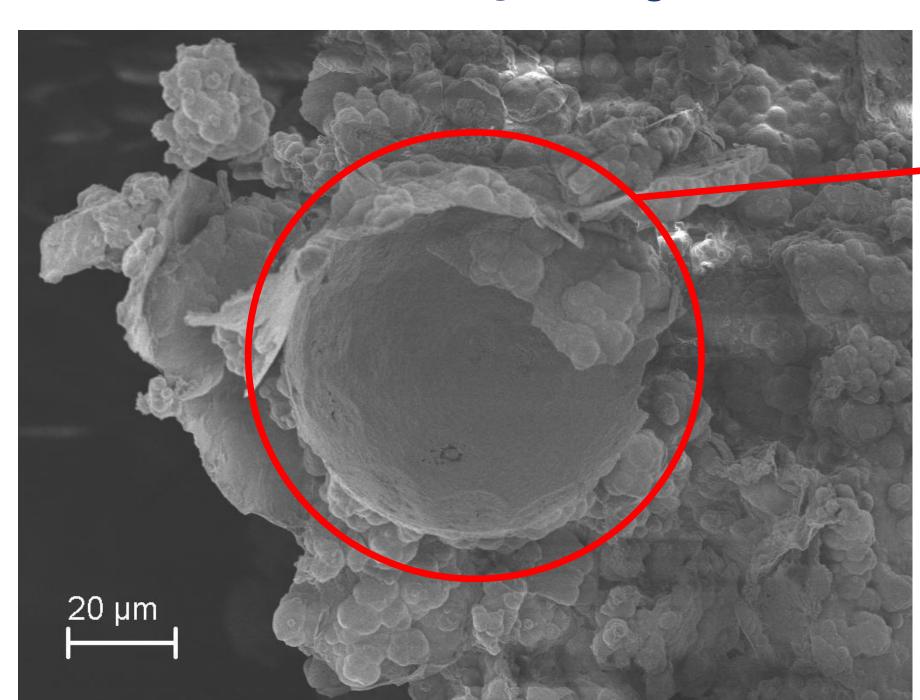


Figure 5. Test Batch 5 SEM Image.

The upconverting nanoparticles are not soluble in DCPD, making the encapsulation of nanoparticles by the *in situ* urea formaldehyde encapsulation process difficult.

Future Work

- The process of *in situ* urea formaldehyde microencapsulation must be perfected or alternative encapsulation methods must be developed.
- Microencapsulated upconverting nanoparticles must be applied to real microelectronics and their effectiveness characterized.



[1] Koushanfar, F., Fazzari, S., McCants, C., Bryson, W., Sale, M., Song, P., & Potkonjak, M. (2012, June). Can eda combat the rise of electronic counterfeiting. 49th annual design automation conference dac '12, San Fransisco, CA.

[2] Brown, E. N., Kessler, M. R., Sottos, N. R., & White, S. R. (2003). In situ poly(urea_formaldehyde) microencapsulation of dicyclopentadiene. Journal of Microencapsulation, 20(6), 719-730.

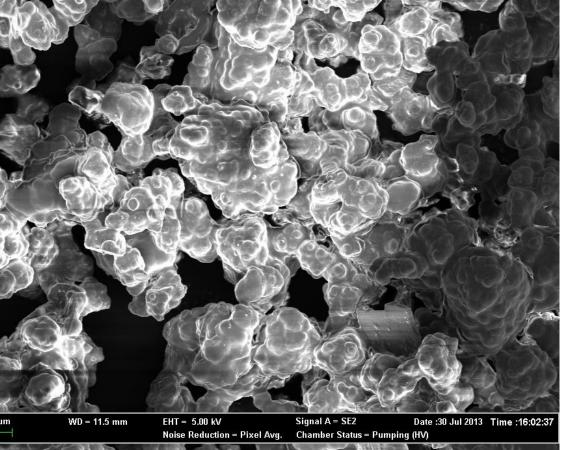
[2] White, S. R., Sottos, N. R., Geubelle, P. H., Moore, J. S., Kessler, M. R., Sriram, S. R., Brown, E. N., & Viswanathan, S. (2001). Autonomic healing of polymer composites. Nature, 409 (6822), 794-797.

Hydrochloric Acid (to adjust pH to

Encapsulant/Nanoparticle-solvent

Mixture is stirred vigorously to create an oil-in-water emulsion and allowed to react between 50-55° C for four hours. The product is filtered in a coarse glass-fritted filter and washed with DI water, ideally leaving behind urea formaldehyde "shells" loaded with the encapsulant and anything dissolved/dispersed in the encapsulant.





Broken Microcapsule